



CyberOptics to Display APS2 Technology at SEMICON Korea

Advanced technology demonstrates increased accuracy and improved sensitivity for airborne particle measurements

Minneapolis, MN—January 19, 2016— [CyberOptics® Corporation](#) (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, will showcase the WaferSense® and ReticleSense® Airborne Particle Sensor (APS2) technology at [SEMICON Korea](#), the largest microelectronics event in Korea, January 27-29, 2016, at the Winix booth (Hole A #2228)

CyberOptics' APS2 improves equipment set-up and long-term yields in semiconductor fabs by wirelessly monitoring airborne particles in real-time. The next-generation APS2 improves on the industry-leading accuracy and sensitivity of the company's devices widely adopted by semiconductor fabs and equipment OEMs worldwide.

"We've invested a significant amount of R&D effort into our product portfolios to continue to develop and evolve the most advanced technologies that generate both time and expense savings for our customers," said Ferris Chen, Director of Sales, CyberOptics, Asia.

The wireless APS2 devices quickly monitor, identify and enable troubleshooting of airborne particles down to .14um within semiconductor process equipment and automated material handling systems. Equipment and process engineers can speed equipment qualification, shorten equipment maintenance cycles and lower equipment expenses with objective and reproducible data. Plus, the new thinner and lighter form factor of the WaferSense APS2 provides greater versatility as it can travel through virtually all tools.

CyberOptics will also demonstrate its new WaferSense and ReticleSense Auto Multi Sensors (AMS/AMSR) that measure leveling, vibration and humidity in an all-in-one wireless real-time device. With its thin and light form factor, the AMS travels through virtually any tool and the AMSR can capture multiple measurements in all locations of the reticle environment. The all-in-one devices are yet another way to increase yield and reduce downtime in semiconductor environments.

About the CyberOptics WaferSense and ReticleSense Line

The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS), the Airborne Particle Sensor (APS), the next-generation Airborne Particle Sensor (APS2) and the new Auto Multi Sensor (AMS) are available in various wafer shaped form factors depending on the device, including 150mm, 200mm, 300mm and 450mm wafer sizes. The ReticleSense measurement portfolio including the Airborne Particle Sensor (APSR & APSRQ) and next-generation APS2, the Auto Leveling System (ALSR) and the new Auto Multi Sensor (AMSR) are available in a reticle shaped form factor.

For more information about the entire line of CyberOptics solutions please visit the company's website at www.cyberoptics.com.

About CyberOptics

CyberOptics Corporation (NASDAQ: CYBE) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics sensors are being used in general purpose metrology and 3D scanning, surface mount technology (SMT) and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of its key vertical segments. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; expectations regarding LDI and its impact on our operations; integration risks associated with LDI and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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